



# EIC\_NET Summary of R&D activities (mainly a 2020 summary + 2021 outlook)



**Many** thanks to the **many** people helped me to put together this presentation!

P. Antonioli INFN/Bologna



As starting point use as reference Andrea's summary at last EIC\_NET meeting (Bari 2019) <a href="https://agenda.infn.it/event/20360/contributions/103554/attachments/68350/84356/EIC\_GENOVA\_CELENTANO.v2.pdf">https://agenda.infn.it/event/20360/contributions/103554/attachments/68350/84356/EIC\_GENOVA\_CELENTANO.v2.pdf</a>



Andrea's last slide Nov 2019

### Caveat:

- many references
- despite many slides, focus on overview not on details
- link to EoI + YR

## **YR SNAPSHOT**

https://indico.bnl.gov/event/9913/attachments/31448/49647/EIC\_YR\_SNAPSHOT\_19NOV2020-75MB.pdf

# Where our R&D fits in?



# all-silicon and hybrid tracking detectors baseline (YR4 "Berkeley")

https://indico.bnl.gov/event/9913/contributions/43313/attachments/31469/49682/2020\_11\_20\_YR\_detector\_concepts\_tracking\_LG\_2.pdf

#### From CDR draft report (table shown by Rolf Ent at YR4)

https://indico.bnl.gov/event/9913/contributions/43303/attachments/31409/49584/EIC Detector CDR 111720.pdf

### + INFN EoI:



### From PID overview YR4:

https://indico.bnl.gov/event/9913/contributions/43315/attachments/31471/49692/PID in the Yellow Report.pptx

system	system components	reference detectors	detectors, alternative options considered by the community				
	vertex	MAPS, 20 um pitch	MAPS, 10 um pitch			1	
tracking	barrel	TPC	TPC <sup>a</sup>	MAPS, 20 um pitch	MICROMEGAS <sup>b</sup>	]	
	forward & backward	MAPS, 20 um pitch	GEMs with Cr electrodes			1	
	barrel	Pb/Sc Shashlyk	SciGlass	W powder/ScFi	W/Sc Shashlyk	1	
FCal	forward	W powder/ScFi	SciGlass	Pb/Sc Shashlyk	W/Sc Shashlyk	1	
ECai	backward, inner	PbWO <sub>4</sub>	SciGlass			1	
	backward, outer	SciGlass	PbWO4	W powder/ScFi	W/Sc Shashlyk <sup>c</sup>	1	
/,	barrel	High performance DIRC & dE/dx (TPC)	reuse of BABAR DIRC bars	fine resolution TOF		1	
i (	forward, high p	fluorocarbon gaseous RICH	double RICH combining	high pressure Ar RICH		]	
h-PID	forward, medium p	aerogel	aerogel and fluorocarbon			]	
	forward, low p	TOF	dE/dx			]	
	backward	modular RICH (aerogel)				•	
e/h separation	forward	TOF & areogel & gaseous RICH	adding TRD		+ DAQ	+ DAQ	
at low p	backward	modular RICH & TRD	Hadron Blind Detector		(streaming	readout)	
HCal	barrel	Fe/Sc	RPC/DHCAL	Pb/Sc			
	forward	Fe/Sc	RPC/DHCAL	Pb/Sc		](+ software	e/computing)
	backward	Fe/Sc	RPC/DHCAL	Pb/Sc		] 3	

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# Vertexing

ALICE



# Contributions to Si-vertex R&D as from INFN EoI:

- already started in the framework of the YR preparation:
  - ✓ MC and detector/physics performance studies (started in the framework of the current YR preparation) → talk Andrea B.
- ongoing for ALICE ITS3, largely synergic in view of EIC (2021-2024):
  - ✓ techniques and tools for thinning, bending and interconnection of wafer-scale MAPS sensors based on 65 nm CMOS process;
  - ✓ pixel-chip sensor test and characterization procedures;
  - $\checkmark$  solutions for cooling, mechanical support structure and assembly procedure.



	<b></b>	Inner Tracking Silicon tech	hno	logy options	BERKELLEY LAB	rence Berkeley National
	ITS3 silicon	design parameters				
	Parameter	Wafer-scale sensor (this proposal)				
	Technology node	65 nm				
	Silicon thickness	20-40 µm	Trac	king detector component	Stave X/X0	
	Chin dimensions	scalable up to 28 x 10 cm				
	Front-end pulse duration	~ 200 ns	ITS3	like vertexing	0.05-0.1%	
	Time resolution	< 100 ns (option: <10ns)			0.550/	
IS I	Max particle fluence	100 MHz/cm <sup>2</sup>	1153	like barrel (up to 1.5 m length)	0.55%	
-	Max particle readout rate	100 MHz/cm <sup>2</sup>	ITCO	like disc (up to 60 cm diamotor)	0 2494	
	Power Consumption	< 20 mW/cm <sup>2</sup> (pixel matrix)	1155	since disc (up to bo cill diameter)	0.24%	
	Fake hit rate	$\leq 10^{-7}$ event/nixel				
	NIEL radiation tolerance	$10^{14}$ 1 MeV n <sub>e9</sub> /cm <sup>2</sup>				
	TID radiation tolerance	10 MRad				
		Si + gaseous		All Si		
		Si i Bascous				
	Attributes for	<ul> <li>dE/dx in gas for PID (TPC)</li> </ul>		<ul> <li>Readout faster than TPC</li> </ul>		
	consideration	Mall understead technology loss		Bottor momentum recolution th	on TPC at high	or
	consideration	• Well understood technology - less		· Better momentum resolution th	an irc at nigh	ier
		R&D needed.		momentum (>~5GeV/c)		
		Costs loss (likely)		Can be made more compact		
		COSts less (likely)		Can be made more compact		
		<ul> <li>Less material in tracking region but</li> </ul>	t	<ul> <li>Less material in endcap regions</li> </ul>		
		more in the endcan region		Very high single point resolution		
		nore in the endeap region.		very man single point resolution	,	
		<ul> <li>Worse single point resolution but</li> </ul>				
		more position samples				
		more position samples				

From YR4 workshop discussing tracking options



R&D activity - EIC\_NET

# Bending



# **Pixel sensor bending**

### Design and production of sensor bending tools

- Prototyping of bending tools for existing sensors
- Extension to wafer-scale sensors
- Bent sensor surfarce description





### INFN-TS/ALICE & ITS3 project





Ref: More on ITS3 results at G. Contin@SVT-EIC workshop

https://indico.jlab.org/event/400/contributions/6536/attachments/5413/6745/EIC\_workshop\_20200903\_Contin.pdf

# Thinning, interconnections and characterization



# Development and validation of wafer thinning techniques

- Target thickness: 20-40 um
- With mechanical and etching processes
- Handling tool development

## Development and application of wire/tab bonding techinques

- Bond-after-bending and bend-after-bonding techniques
- Design and production of bendable printed circuits
- Design and production of bonding tools for bent silicon



### Chip performance comparison bent/flat

- Electrical tests and standalone characterization
- Detection efficiency and cluster shape in testbeams

## 65 nm CMOS process sensor characterization

- Test structures
- Sensor prototypes
- Wafer-scale sensors













Silicon Genesis: 20 micron thick wafer

## INFN-TS/ALICE & ITS3 project

# Mechanics & cooling



### selection/characterization of carbon foam materials (structural/thermal prop.)

Due to the difficulty in accurately modelling all the details that influence the performance of the cooling system, experimental tests will be performed in order to validate the results o initial Computatation Fluid Dynamics (CFD) simulations. The vibrational response and the position stability of the large curved sensor areawill be assessed by Finite Element Modal and Dynamic Response Analysis. CFD analysis will be used to simulate the forced air flow between the layers and will aim to drive the design of the carbon-foam heat exchanger rings, for optimum thermal management. Different carbon foams with best thermal properties and low-pressure drop, as well different configuration patterns will be analysed. Their shape will be optimized to reduce impedance and to achieve the best flow distribution and the optimum angles between the half-layer and the flow direction. The definition of a correct CFD model will require experimental tests, aiming at measuring the heat transfer and pressure drop across different samples of porous carbon foam.

## development of the assembly procedure

it must allow bending to shape the half-layers and freezing the position in the detector barrel layout. Verify achieved halflayers positions through metrology. Glued joints/procedures will be developed in order to guarantee the best mechanical/thermal connections. Develop all the necessary tooling to provide alignment reference

### development and production of prototype support structures

Similar aspects now under investigation for the developing of the ITS3 structural support can be faced for R&D steps of the new EIC detector. Carbon foam parts as rings and/or bars will be the baseline for the mechanics and cooling systems. Additional sheet in carbon fibre could be used to improve the connection in the glued joints and for a more stable alignment between layers and other parts (FPC, external support structure, ventilation system, etc.)

## development of tooling for the assembly procedure

Vacuum jig will be used for the first precision alignment of the sensors. An optical system combined with a micrometrical movement chuck (manual or automatic) will guarantee the correct alignment between chips and a vacuum mandrel for the chip bending step. Different moulds will provide and fix the nominal position of the bent chips during the glue polymerization phase. An external reference system will guide all the vacuum jigs and mandrels in the sequential assembly steps.





This approach is being mirrored / visible in Italy (work presented so far was under ALICE, now - since 2021 – factorized in EIC NET!)

ptember 2-4, 202

https://indico.jlab.org/event/400/contributions/6533/attachments/5409/6741/EIC-SVT-Si-ITS<sub>3</sub>/EIC projects overlap

□ The ALICE ITS3 project aims at developing a new generation MAPS sensor at the 65 nm node with extremely low mass for the HL-LHC

- See Giacomo's talk

Outlook

- □ As presented by Leo Greiner (LBNL) at the EIC Yellow Report Kick-Off meeting, this effort is particularly interesting for the EIC
  - The ITS3 sensor specifications and development timescale are largely compatible with those of the EIC
  - Non-ALICE members are welcome to contribute to the R&D to develop and use the technology for other applications
- Joining the ITS3 collaboration, the EIC can leverage on a large effort at CERN, sharing development costs, to design an innovative sensor solution at the 65 nm node, suited for an experiment starting in ~ 2030

This has been identified has the most efficient way forward





aerogel gas psTOF(10ps)

(taken from: <a href="https://www.jlab.org/user resources/meetings/JLUO 6 19/Romanov.pptx">https://www.jlab.org/user resources/meetings/JLUO 6 19/Romanov.pptx</a>)

http://www.eicug.org/web/sites/default/files/EIC\_HANDBOOK\_v1.2.pdf

Simulations show that in order to satisfy the physics goals of the EIC, it is desirable to provide  $\pi/K$  identification in the central barrel up to 5-7 GeV/*c*, in the electron-going endcap up ~10 GeV/*c*, and in the hadron-going endcap one would need to reach ~50 GeV/*c*.

INFN very active with many groups (BA, BO, FE, LNF, LNS, RM1, TO, TS) under two EIC eRD-initiatives (eRD-6 and eRD-14)

Required large *p* coverage brings to RICH technique, with challenges @EIC associated to radiators and photodectors

- dual-radiator RICH → R&D on photodetectors ("B immune") – wide λ range
- windowless CsI-based gas photodector (MPGD) narrow  $\lambda$  range

https://wiki.bnl.gov/eic/upload/ERD6\_ProgressReport\_201907.pdf https://wiki.bnl.gov/conferences/images/8/8e/ERD14\_Jan-2020.pdf

# dRICH: the idea





- simulations -
- design prototype towards procurement  $\rightarrow$  test beam in 2021 -
- sensors + readout electronics study



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# dRICH: optimizing design and preparing prototype $\rightarrow$ test beam 2021



11

momentum [GeV/c]

polar angle [deg]



# Sensors for RICH: SiPM

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dRICH Key Hardware Components 2/2						
Component	Function	Specs/ Requirements	Risk	Mitigation		
Photon Detector	Single photon spatial detection	Magnetic field tolerant and radiation hardness; ~ few mm spatial resolution	MCP-PMT is likely duable, but expensive. Need to find alternatives	LAPPD may represent an alternative. <b>R&amp;D on SiPM:</b> a promising, quicky improving, wordwide pursued, and cheap technology.		
Electronics	Amplify and shape single photon analog signal, convert to digital, transfer to DAQ nodes	Low noise Time res. ~ 0.5 ns μs signal latency; High density	No major risk but need to be tailored to photon sensors	MIAROC3 based readout available for prototyping; final choice will depend on sensor. ASIC development for optimised streaming readout (discrimination vs sampling)		

## EIC R&D committee explicitly asked for such a program

In-depth EIC R&D Review Report (11/25/2019): "An important remaining issue is the SiPM noise rate after irradiation which should be clarified. We expect that it will take 2-3 years to fully understand if SiPMs can be used in RICH detectors at EIC".

18th EIC R&D Meeting Report (01/30/2020): "The committee again recommends the group to re-examine options that do not rely on waveform sampling, e.g., a TOT-based design like the TOPFET2 ASIC, which is radiation hard, has low power consumption and has achieved a very good resolution per single photon with SiPMs."

R&D needed for SiPM:

- 1. Proof of "feasibility": DCR & operating conditions, single photon detection etc.
- 2. Readout electronics: ASIC (+ streaming readout)
- 3. Radiation tolerance
- "dRICH based" for test beams and parameters selection, but expected R&D outcome might extend beyond

Groups involved: FE, LNF, RM1, CT, BO, TO, TS "new" activity since 2020 used to "build the plan" → 2021 to deliver results

- 6 x 4500 cm<sup>2</sup> = **O(3 m<sup>2</sup>)** active sensors
- 3x3 mmxmm pixel size
- $\rightarrow$  Single Photon Detection (**PDE**  $\uparrow$ )
- → **Temperature** vs DCR ("not cryogenic")
- → Use **timing** to help filter DCR
- → Radiation tolerance (expected@EIC 10<sup>11</sup> n<sub>eq</sub>/cm<sup>2</sup>)
- → Sampling vs discrim. + TOT



# Front-End electronics for SiPM



#### ALCOR - A Low Power Chip for Optical Sensor Readout





#### 32-pixel matrix mixed signal ASIC

- the chip performs amplification, signal conditioning and event digitisation, and features fully digital I/O.
- each pixel reads an SiPM (up to 1 cm<sup>2</sup>, compatible with smaller pixels)
- Pixel hosts SiPM VFE, leading-edge discriminator, 4 TDCs, charge integrator, digital control and interface
- Single-photon time tagging mode or time and charge measurement
- 64-bit (32-bit on time tagging mode) event and status data is generated on-pixel and propagated down the column
- Up to 4 LVDS TX data links used, SPI configuration
- operation from 10 MHz up to 320 MHz (TDC binning down to 50 ps)
- 10 MHz clock, 500 ps r.m.s. time resolution on single photon



FEE2018 Jou

- Test of the ASIC expected to end by ~2020
- Based on 2020 results and coupling with SiPM → 2022 for an ALCOR v2.0 better tailored for EIC requirements

"smoke test done, absorption ok (6 mW/ch), comms. test with FPGA on-going"

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### ALCOR:

R&D activity - EIC NET summary

- Developed by INFN Torino originally for a Darkside application
- Optimized for cryo operation
- First samples received from foundry in 2020
- Specs would match at first order requirements for EIC, but an ALCOR++ optimised for RICH application will be next step
- INFN Torino  $\rightarrow$  characterization with a FBK SiPM sensor
- INFN Bologna → development of readout card FPGA-based (connected to ASIC carrier via fast serial links: as in DAQ for ARCADIA)



INFN-TO

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ALCOR Testboard <u>M.Mig</u>none 06/2020

 $\circ$ 

# "Drawing phase"



## SiPM Readout

Activity in the last 3 months:

#### 5x SiPM Carriers

Hamamatsux2, SensL, Bradcom, FBK Minimum components + edge connector for irradiation and anneling Stage: design and procurement

#### 2x Adapters\_base

Slow and fast SiPM signals Direct connection for characterization Stage: design and procurement

#### 2x. Adapter\_alcor

Slow and fast SiPM signals Connection to ALCOR and Firefly readout Stage: design

- 1x ALCOR test board ALCOR chip validation Stage: delivered and under test
- 1x FireFly DAQ ToT based readout Stage: under development and test





INFN FE/BO/TO

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# Sensors for RICH: MPGD-based photon detectors



R&D activity - EIC NET summary

**INFN-BA/T** 





### https://arxiv.org/abs/2006.10447 https://arxiv.org/abs/1908.05052

prototype with 3.5 x 3.5 mm<sup>2</sup> pads (mini-pad prototype) quartz radiator

Noise studies (from lab+test beam data 2018): noise level too high for single photon detection:

 $3\sigma$  thr @ 10 k electrons eq!

too noisy to determine spatial resolution + efficiency limited at 70%



# Optimizing the minipad prototypes

Various improvement strategies to reduce noise problems modifying: HV distribution + FE electronics + PCB design



resistor cards providing HV to individual pads near and parallel to FEE cards

**INFN-TS** 

Moving from APV25 to VMM read-out board based: - low noise at high C + trigger less operations



APV25: https://cds.cern.ch/record/1069892/files/cer-002725643.pdf VMM: http://cds.cern.ch/record/2093606/files/ATL-MUON-SLIDE-2015-822.pdf?version=1 Vertical vias to minimize crossing signal lines + equalization of signal line length (same input capacitance)



Actually, this was already the 2020 plan, highly penalized by COVID (lab closed @INFN-TS)  $\otimes \rightarrow$  moving these studies to 2021

MM for comparative

MMFE1

SRS-APV25

# Radiators for RICH: aerogel

- Aerogel critical component behind dRICH design. Currently two main producers Budker (Russia) [CLAS12 supplier] (hydrophobic) and Chiba University (hydrophilic)
- <u>2020 Developments (INFN-BA) Meeting with Belle II experts (I. Adachi and M. Tabata) on 15th of May</u>
  - Reviewed main production procedures and aerogel parameters, good improvement of transparency (*I*<sub>scatt</sub> = 70 mm at 400 nm for n ~ 1.03-1.05)
  - Production timeline: 60 batches of 28 tiles of 18x18x2 cm<sup>3</sup> in 1 y, to cover 25 m<sup>2</sup> with two layers assuming a yield of 60% one needs 90 batches ~ 1.5 y
  - Cost ~ 10 kEuro/ batch
- Aerogel samples procurement with LHCb from Chiba University in progress, (agreement with LHCb for common R&D) → Optical characterization to be performed in lab and test-beam
- Synergy with an ALICE initiative (consider a RICH within ALICE 3.0 to complement TOF at high-p)











# Aerogel for RICH: simulations and synergies



Synergies



access to a 2<sup>nd</sup> potential provider for aerogel (a radiator critical for RICH@EIC)

→ ALICE

R&D for the silicon-based sensor (which could possibly allow both MIPs and single photon detection)  $\rightarrow$  see SiPM studies (radiation tolerance, Single Photon + timing)

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R&D activity - EIC\_NET summary

# Radiators for RICH: Argon



Ref. Silvia@YR1 ("Philadelphia"): <a href="https://indico.bnl.gov/event/7449/contributions/35912/attachments/27095/41303/DallaTorre\_RICH\_high-p\_March2020\_Temple.pdf">https://indico.bnl.gov/event/7449/contributions/35912/attachments/27095/41303/DallaTorre\_RICH\_high-p\_March2020\_Temple.pdf</a>

The issue: fluorocarbon gas mixtures are not eco-friendly!

GWP: CF4 4400, C2F6 6200, C4F10 4800

Why fluorocarbon? "dense" → many photons small chromaticity → good angular resolution

Idea: use noble gas (Ar) at high pressure (low chromaticity and make it dense)

- → develop vessel studies (keep high pressure/limited material budget) + simulations (LNS/BA)
- $\rightarrow$  test with dRICH prototype (FE, RM1, LNF)
- → (at Stonybrook activity looking at MPGD operating at high pressure)



→ not easy to predict availability & costs in ten years from now

### PRESSURIZED Ar vs FLUOROCARBONS



# Streaming Readout (SRO) (+ calorimetry)





# SRO: validate the new DAQ approach



### As eRD23 + YR, INFN is contributing to define a SRO framework for EIC by defining the EIC SRO specs $(YR) \rightarrow$ new FE electronics on-site + testing solutions @JLab (Hall-B and Hall-D)

HallD parasitic test beam area,

triggered DAQ (parasitic mode)

INFN WaveBoard fADC for SRO tests

SRO DAQ cabled/connected and tested

Data analysis in progress

to ~ 4.5GeV lepton

for software L2 trigger

# Streaming readout activity @ INFN 2019/2020

- We participate to the eR&D-23 activity: monthly phone meetings and dedicated workshops (twice per year).
  - Last meeting: May 2020 (remote-only)
- Strong involvement in the EIC »Yellow Report» initiative.

DAO/Electronics

- A. Celentano is co-convener of the «Readout and DAQ» working group.
- Main experimental activity: validation of the new DAQ approach.



#### **Dedicated personel:**

- 1 post-doc hired to work through "Ministero degli Esteri progetti di Grande Rile"
- 1 master thesis student, currently applying to PhD program

On-Beam tests at JLab/Hall-D: a matrix of PbWO+SiPM has been exposed to 4 GeV secondary electron/positron beam using the WaveBoard as front-end readout and TRIDAS + JANA as back end

Strong involvement in the YR activity and development/test of the FE digitiser (WaveBoard) designed by INFN-RM1 and INFN-GE.

# 2020 SRO VI workshop

https://indico.jlab.org/event/378/

# **Streaming RO - Hall-D tests**

V.Berdnikov, T.Horn





SiPM(left) & PMT(right) cal. prot.

Waveboard



# The SRO "demonstrator" at JLab – Hall B (I)





 On beam test in Hall-B used the INFN CLAS12 Forward Tagger as a bench test for a SRO DAQ





# The SRO demonstrator (II)





[JLAB Digitizer + VTP (SRO-ready)] + TRIDAS (KM3-NET) + JANAS (GLUEX) → scaled up to 600 channel

### **Run | Data analysis**

S.Vallarino, A.Celentano



- Based on positive results, join effort JLab/INFN-BO to build a possible ٠ EIC SRO framework to be tested with the whole CLAS12 detector
- Expected a deeply involvement of INFN-CNAF in the SRO framework in 2021
- August 2021 target integration up to **5000 ch** + more detectors in Hall-B

Credit: F.Ameli, M.Bondi, R De Vita, T.Chiarusi, C. Fanelli, L.Marsicano, P.Musico, C.Pellegrino, S.Vallarino R&D activity - EIC

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Preliminary results demonstrated the validity of the framework

Data analysis is still in progress



### First use of AI/ML in a real-time Streaming DAQ system



• Run I: off-line only • Run2: real time!

A tentative mapping summary & outlook....

R&D focus	INEN	impact on	INEN synergies	FIC synergies	
R&D IOCUS		impact on	Intra synergies	LIC Syllergies	
MAPS/ITS3	BA/TS	detector	ALICE	EIC is joining ITS3	
dRICH	FE/RM1/LNF/CT	detector	CLAS12	eRD14	
SiPM	BO/FE/TO/TS	sensor + FEE	DARKSIDE (ARCADIA)	eRD14	
MPGD	BA/TS	sensor + FEE	COMPASS (ATLAS)	eRD6	
aerogel	BA/BO	radiator	ALICE		
high pressure Ar	BA/LNS/TS	radiator		Stonybrook	
calorimetry	GE/RM1	detector		eRD1 / CUA	
streaming readout	GE/RM1/(BO/CNAF)	DAQ	KM3-NET	eRD23	
B&D well integrated with FIC main initiatives     (+ eRD20 simulations)					

- R&D well integrated with EIC main initiatives ٠
- strong synergy for **tracking** with ALICE: ٠
  - 2020 was a good year to integrate this in EIC flow
- promising contributes in different **PID** areas: ٠
  - 2021 will be a key year to deliver results needed to ٠ steer choices
- we are leading as <u>coordinator</u> the SRO proposal. Other INFN streams of work should now become part of this integration/demonstration effort 3/12/2020 - P. Antonioli R&D activit

system	system components	reference detectors	detectors, alternative option	ns considered by the com	munity	_
	vertex	MAPS, 20 um pitch	MAPS, 10 um pitch		-	-
tracking	barrel	TPC	TPC *	MAPS, 20 um pitch	MICROMEGAS	b
	forward & backward	MAPS, 20 um pitch	GEMs with Cr electrodes			
	barrel	Pb/Sc Shashlyk	SciGlass	W powder/ScFi	W/Sc Shashlyk	
ECal	forward	W powder/ScFi	SciGlass	Pb/Sc Shashlyk	W/Sc Shashlyk	
ECal	backward, inner	PbWO <sub>4</sub>	SciGlass			
	backward, outer	SciGlass	PbWO4	W powder/ScFi	W/Sc Shashlyk c	
,	barrel	High performance DIRC & dE/dx (TPC)	reuse of BABAR DIRC bars	fine resolution TOF		
	forward, high p	fluorocarbon gaseous RICH	double RICH combining	high pressure Ar RICH		
h-PID	forward, medium p	aerogel	aerogel and fluorocarbon			
	forward, low p	TOF	dE/dx			
·،	backward	modular RICH (aerogel)				-
e/h separation	forward	TOF & areogel & gaseous RICH	adding TRD		+ I	DAQ
at low p	backward	modular RICH & TRD	Hadron Blind Detector		(sti	reaming readout)
	barrel	Fe/Sc	RPC/DHCAL	Pb/Sc		
HCal	forward	Fe/Sc	RPC/DHCAL	Pb/Sc		1
	backward	Fe/Sc	RPC/DHCAL	Pb/Sc		3



### (all this despite a very difficult 2020 R&D Zoom-mode)

Sunday November 01, 2020 Can You Zoom Now

### DILBERT



